

WE CLAIM:

1           1.       A mating assembly for detachably attaching a device to a mechanical substructure,  
2       said assembly comprising in combination:

3                   a) a pair of rails disposed on and coupled with opposed sides of the device;

4                   b) a pair of spaced apart guides mounted upon the substructure for slidably  
5       engaging and mating with said pair of rails upon attachment of the device to the substructure;

6                   c) a cross member interconnecting said pair of rails; and

7                   d) securing means for securing said cross member to the substructure.

1           2.       A mating assembly as set forth in Claim 1 including a spring extending from one  
2       rail of said pair of rails for electrically contacting a guide of said pair of guides to discharge any  
3       static charge present.

1           3.       A mating assembly as set forth in Claim 2 including at least one contact plate  
2       extending from the substructure for sliding engagement with said spring.

1           4.       A mating assembly as set forth in Claim 1 including a first electrical connector  
2       attached to the device for engaging a second electrical connector mounted on the substructure  
3       upon attachment of the device to the substructure.

1           5.       A mating assembly as set forth in Claim 4 including an alignment pin extending  
2       from a rail of said pair of rails for engaging a hole in a guide of said pair of guides to align said

3 first and second electrical conductors with one another.

1 6. A mating assembly as set forth in Claim 5 including a spring extending from one  
2 rail of said pair of rails for electrically contacting a guide of said pair of guides to discharge any  
3 static charge present.

1 7. A mating assembly as set forth in Claim 6 including at least one contact plate  
2 extending from the substructure for sliding engagement with said spring.

1 8. A mating assembly as set forth in Claim 1 wherein each guide of said pair of  
2 guides are identical.

1 9. A mating assembly as set forth in Claim 8 wherein each guide includes an  
2 overhang adapted for slidable engagement with a respective rail of said pair of rails.

1 10. A mating assembly as set forth in Claim 1 including at least one contact plate  
2 extending from the substructure and at least one recess disposed in a guide of pair of guides for  
3 receiving said contact plate.

1 11. A mating assembly as set forth in Claim 10 including a spring extending from one  
2 rail of said pair of rails for slidably engaging said contact plate to dissipate any electrostatic  
3 charge present upon attachment of the device to the substructure.

1           12.     A mating assembly as set forth in Claim 1 wherein the device includes a housing  
2 adapted for coupling said pair of rails thereto.

1           13.     A mating assembly as set forth in Claim 1 wherein the substructure includes an  
2 apertured face plate for penetrably receiving the rail mounted device.

1           14.     A mating assembly as set forth in Claim 13 wherein said securing means is  
2 adapted to secure said cross member to the face plate.

1           15.     A method for detachably attaching a device to a substructure, said method  
2 comprising the steps of:

3                   a) attaching a pair of rails to opposed sides of the device;

4                   b) slidably engaging the pair of rails with a pair of guides mounted on the  
5 substructure;

6                   c) repositioning an alignment pin extending from one of the rails with a hole in  
7 one of the guides to align an electrical connector of the device with an electrical connector  
8 mounted on the substructure;

9                   d) securing a cross member interconnecting the pair of rails with a face plate  
10 attached to the substructure to secure the device with the substructure; and

11                  e) dissipating any attendant electrostatic charge upon execution of said step of  
12 sliding.

1           16.     The method as set forth in Claim 15 wherein said step of dissipating includes the  
2     step of translating a spring extending from a rail along the corresponding one of the guides.

1           17.     The method as set forth in Claim 16 including the step of contacting a plate  
2     secured in the guide and extending from the substructure with the spring during execution of said  
3     step of translating.

1           18.     A mating assembly for detachably attaching a device to a mechanical substructure,  
2     said assembly comprising in combination:

3                   a) a pair of rails disposed on and coupled with opposed sides of the device;

4                   b) a pair of spaced apart guides mounted upon the substructure for slidably  
5     engaging and mating with said pair of rails upon attachment of the device to the substructure;

6                   c) at least one electrostatic discharge contact electrically coupled with the  
7     substructure;

8                   d) an electrostatic discharge spring extending from one rail of said pair of rails for  
9     electrically contacting said electrostatic discharge contact to discharge any static charge present  
10    in the device;

11                  e) a cross member interconnecting said pair of rails; and

12                  f) securing means for securing said cross member to the substructure.

1           19.     A mating assembly as set forth in Claim 18 including an alignment pin extending

2 from a rail of said pair of rails for engaging a hole in a guide of said pair of guides to align said  
3 first and second electrical conductors with one another.

1 20. A mating assembly as set forth in Claim 18 wherein said at least one electrostatic  
2 discharge contact is recessed in at least one guide of said pair of guides.

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